To the Honorable Commissioner o	of Pat
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102307952

1. Name of	conveying party(ies):	2. Name and address of receiving party(ies):
	Howard E. Rhodes Richard H. Lane 17 -9 - 22	Name: Micron Technology, Inc.
Additional na	me(s) of conveying party(ies) attached?Yes <u>X_</u> No	
3. Nature o	f conveyance:	Street Address: 8000 South Federal Way
X Assignm	nent _ Merger	
_ License	Agreement Change of Name	City: Boise State: ID ZIP: 83707
Execution D	ate: a. October 23, 2002; b. October 22, 2002	Additional name(s) & address(es) attached? Yes X.No
4. Applicat	ion number(s) or patent number(s):	Ę, v
lf this do	ocument is being filed together with a new applicatio	n, the execution date of the application is:
A.	Patent Application No. 10/230.887	B. Patent No(s).
Titl	e: METHOD FOR FORMING CONDUCTIVE MA	ATERIAL IN OPENING AND STRUCTURE REGARDING SAME
Additional nu	mbers attached? Yes X No	
	d address of party to whom correspondence document should be mailed:	6. Total number of applications and patents involved: 1
Name: Mark J. Gebhardt		7. Total fee (37 CFR §3.41): \$40.00
	MUETING, RAASCH & GEBHARDT, P.A. P.O. Box 581415 Minneapolis, MN 55458-1415	X Enclosed Authorized to be charged to deposit account
	Customer Number 26813	8. Please charge any additional fees or credit any overpayments to Deposit account number: <u>13-4895</u>
	DO NOT U	SE THIS SPACE
9. Statemer	nt and signature.	
	of my knowledge and belief, the foregoing information original document.	on is true and correct and any attached copy is an original or a true A Lec 2002
Mark J. Gel Name of Per		Date
	Total number of pages including cover	r sheet, attachments, and document(s): 3
	1	

PATENT REEL: 013555 FRAME: 0335

ASSIGNMENT

Whereas We, Howard E. Rhodes and Richard H. Lane, with residences and citizenships as indicated below; have made an invention in

METHOD FOR FORMING CONDUCTIVE MATERIAL IN OPENING AND STRUCTURE REGARDING SAME

Filed: August 29, 2002 Serial No.: 10/230,887

and executed an application for Letters Patent of the United States of America based thereon;

Now, therefore, for good and valuable consideration, receipt of which is acknowledged, we have individually and jointly agreed to assign and transfer and do hereby assign and transfer unto Micron Technology, Inc. ("Company"), a corporation of Delaware, having its principal office at 8000 South Federal Way, Boise, Idaho, 83707, its successors and assigns, the entire right, title, and interest in and to said invention and application, and in and to any division or continuation (in whole or in part) of said application, and in and to any and all improvements in said invention made by us or any of us or made jointly with others (provided any such improvement is made during, or within one year after the termination of, the employment by the Company of whichever of us, solely or jointly with one or more others, has made the same), and in and to any and all Letters Patent, reexaminations, reissues, or extensions thereof, of the United States of America and countries foreign thereto (including the right to apply for Letters Patent, Utility Models, or Inventors' Certificates in foreign countries in its own name and to claim any priority rights for such foreign applications to which such applications are entitled under international conventions, treaties, or otherwise), which have been or may be granted thereon or on any continued prosecution application, divisional, continuation (in whole or in part), renewal, reexamination, reissue, or other or further application based in whole or in part upon said invention or improvements thereon, to be held and enjoyed as fully and exclusively as they would have been by us or any of us had this assignment and transfer not been made;

We do further agree for ourselves and for our heirs, executors, and administrators, to execute and deliver without further consideration any further applications, assignments, and documents, and to perform such other acts as we lawfully may, that may be deemed necessary by the Company, its successors, assigns, and nominees, fully to secure its right, title, and interest as aforesaid and to obtain or maintain Letters Patent, Utility Models, or Inventors' Certificates in any and all countries;

And we do hereby authorize and request the Commissioner of Patents to issue any and all Letters Patent which may be granted upon any of said applications, to <u>Micron Technology</u>, <u>Inc.</u> as the assignee of the entire right, title, and interest therein.

In witness whereof, we have hereunto signed our names on the days and years set forth below.

Name: Howard E. Rhodes

Address: 631 E. Ridgefield Drive Boise, Idaho 83706

Zissenden

Citizenship: US

STATE OF Fdaho) ss

COUNTY OF Ada

On this 23-day of October 20 02, before me personally appeared Howard E. Khodes, to me known to be the person described in and who executed the foregoing instrument, and he/she executed the same for the uses and purposes therein set forth.

Notary Public

BISSENDING OTAP THE MANAGEMENT OF TO A STATE OF TO A STATE

PATENT REEL: 013555 FRAME: 0336 Assignment Serial No. 10/230,887 Filed: August 29, 2002

Assignment Page 2 of 2

For: METHOD FOR FORMING CONDUCTIVE MATERIAL IN OPENING AND STRUCTURE REGARDING SAME

Name: Richard H. Lane

Address: 204 W. State Street, Boise, Idaho, 83702

Citizenship: US

STATE OF Fdaho

COUNTY OF ____

On this 22nd day of October 2002, before me personally appeared Richard H. Lane, to me known to be the person described in and who executed the foregoing instrument, and he/she executed the same for the uses and purposes therein set forth.

) ss.

Notary Public

RECORDED: 12/09/2002

PATENT

REEL: 013555 FRAME: 0337

Date